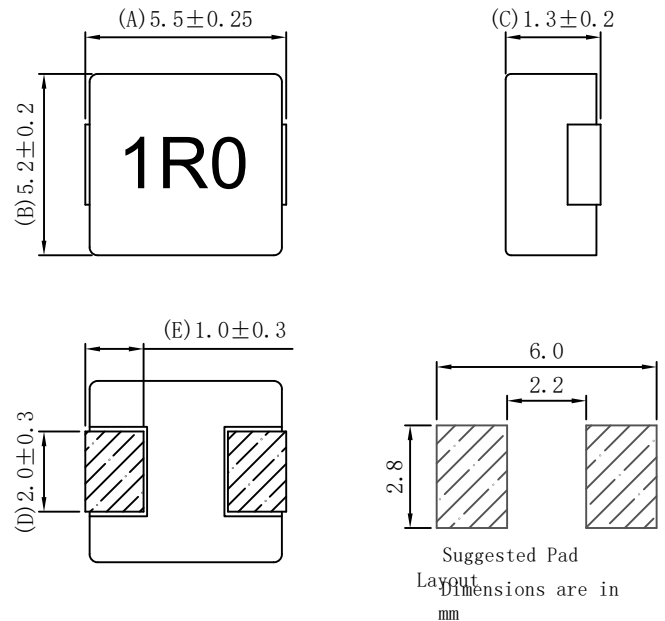


## FEATURES

- RoHS compliant,UL94V-0
- Small size (5.75\*5.4mm Max),low profile(Height:1.5mm Max)
- Inductance range from 0.33uH to 15.0uH
- Surface mount design
- Magnetic shield construction
- Ultra low buzz noise due to composite construction
- Handle transient current spikes without saturation
- Excellent temperature stability for inductance and saturation
- Tape & reel packing
- Solder profile acc.J-STD-020D

## APPLICATIONS

- Low profile ,high current power supplies
- DC/DC converters
- Battery powered devices
- PDA/notebook/desktop/server applications



Part number	Inductance ( $\mu\text{H} \pm 20\%$ )	DCR (m $\Omega$ ) @25 $^{\circ}\text{C}$		Irms (A)	Isat (A)
		TYP.	MAX.		
MHA0515NSGR33M	0.33	8.00	9.00	10.00	15.00
MHA0515NSGR47M	0.47	10.80	12.70	9.00	12.70
MHA0515NSGR68M	0.68	13.50	15.50	8.10	9.50
MHA0515NSG1R0M	1.00	20.00	23.00	6.50	9.00
MHA0515NSG1R2M	1.20	29.30	33.70	5.30	8.00
MHA0515NSG2R2M	2.20	58.00	64.00	3.30	6.00
MHA0515NSG3R3M	3.30	65.00	72.00	3.20	5.00
MHA0515NSG4R7M	4.70	95.00	106.0	3.00	4.00
MHA0515NSG6R8M	6.80	120.0	130.0	2.50	3.20
MHA0515NSG100M	10.0	153.0	170.0	2.00	3.00
MHA0515NSG150M	15.0	310.0	350.0	1.00	2.30

## ABSOLUTE MAXIMUM RATINGS

Operating temperature rang (Including coil' self temperature rise)	-55 $^{\circ}\text{C}$ to +125 $^{\circ}\text{C}$
Storage temperature rang	-55 $^{\circ}\text{C}$ to +125 $^{\circ}\text{C}$

## SOLDERING INFORMATION

Peak reflow temperature	250 $^{\circ}\text{C}$
Pin finish	tin

## PACKAGING INFORMATION

Tape&Reel	3000pcs per reel
Weight	0.22g/pcs

## Notes

1. Electrical specification at 25 $^{\circ}\text{C}$ .
2. Inductance tested at 100 kHz, 0.25Vrms.
3. Irms is the current that caused a approximate 40 $^{\circ}\text{C}$  temperature rise from 25 $^{\circ}\text{C}$  ambient.
4. Isat is the DC current at which inductance drop approximately 30% from its value without current.
5. The part temperature(ambient + temp.rise) should not exceed 125 $^{\circ}\text{C}$  under worst case operating conditions.Circuit design,component placement, PWB trace size and thickness,airflow and other cooling provisions all affect the part temperature.Part temperature should be verified in the end application.